ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V _{CC})+7V Input Voltage (V _{IN})±30V	
Output Short-Circuit Current	
(Shorted to GND or V _{CC}) (Note 1)Self Limiting	
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
Plastic DIP (derate 10.00mW/°C above +70°C)800mW	
SO (derate 8.7mW/°C above +70°C)695mW	

Operating Temperature Ranges	
MAX1489EC_D	0°C to +70°C
MAX1489EE_D	40°C to +85°C
Storage Temperature Range	65°C to +160°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 5V \pm 10\%, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted. Typical values are at $V_{CC} = 5V$, $T_A = +25^{\circ}C$.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DC CHARACTERISTICS		I		I			1
			I _{OUT} = -20μΑ	3.5	4.99		V
Output Voltage High	Voн	$V_{IN} \le 0.4V$	I _{OUT} = -3.2mA	2.5	4.41		
Output Voltage Low	Vol	V _{IN} ≥ 2.4V, I _{OUT} = 3.2mA			0.17	0.4	V
Output Short-Circuit Current (Note 1)	los	Shorted to GND		-35			mA
		Shorted to V _{CC}	Shorted to V _{CC}			60	
Supply Current	Icc				260	600	μA
Input Voltage Range	VIN			-25		25	V
Input Voltage High	ViH			1.60	2.17	2.60	V
Input Voltage Low	VIL			0.75	1.06	1.30	V
Input Hysteresis	V _{HYST}				1.11		V
Input Resistance	RIN			3.0	5.0	7.0	kΩ
TIMING CHARACTERISTICS				•			•
Output Propagation Delay, Low to High	tplh	Figure 1		1.38		4.0	μs
Output Propagation Delay, High to Low	tphl	Figure 1		1.45		4.0	μs
Output Propagation Delay Skew, [tpLH - tpHL]	tskew	Figure 1			70		ns
Output Transition Time	t _{TR}	V _{OUT} = 10% to 90%			35	120	ns
Input Noise Rejection	t _N	Pulse amplitude = 5V (Note 2)			1.0		μs
Guaranteed Data Rate	DR			120	240		kbps
ESD CHARACTERISTICS	1	1		I			
		Human Body Mod	lel		±15		
ESD Protection		IEC1000-4-2 (Con	tact Discharge)		±8		kV
		IEC1000-4-2 (Air-0	Gap Discharge)		±15		1

Note 1: Only one output may be shorted at a time.

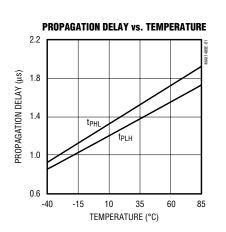
Note 2: See Noise Pulse Rejection graph in Typical Operating Characteristics section.

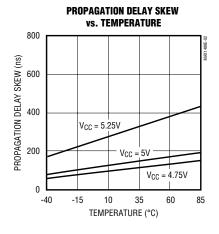
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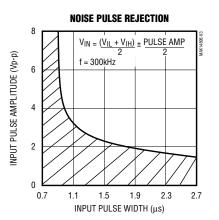


Typical Operating Characteristics

(V_{CC} = 5V, T_A = +25°C, unless otherwise noted.)







Pin Description

PIN	NAME	FUNCTION
1, 4, 10, 13	INPUT_	Receiver Inputs
2, 5, 9, 12	N.C.	No Connect—not internally connected
3, 6, 8, 11	OUTPUT_	Receiver Outputs
7	GND	Ground
14	Vcc	Supply Voltage

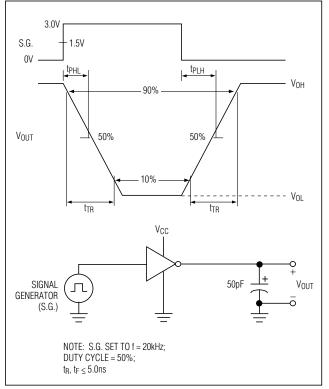


Figure 1. Timing Diagram

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MAX1489E

M/IXI/M

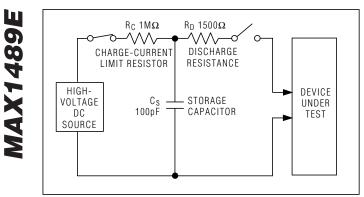


Figure 2a. Human Body ESD Test Model

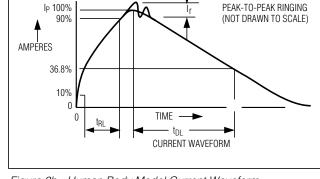


Figure 2b. Human Body Model Current Waveform

Human Body Model

Figure 2a shows the Human Body Model, and Figure 2b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5k\Omega$ resistor.

IEC1000-4-2

/N/IXI/N

The IEC100-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX1489E helps you design equipment that meets Level 4 (the highest level) of IEC1000-4-2, without additional ESD protection components.

The major difference between tests done using the Human Body Model and IEC1000-4-2 is higher peak current in IEC1000-4-2. Because series resistance is lower in the IEC1000-4-2 ESD test model (Figure 3a), the ESD withstand voltage measured to this standard is generally lower than that measured using the Human Body Model. Figure 3b shows the current waveform for the ±8kV IEC1000-4-2 Level 4 ESD Contact Discharge test.

The Air-Gap test involves approaching the device with a charged probe. The Contact Discharge method connects the probe to the device before the probe is energized.

Detailed Description

±15kV ESD Protection

As with all Maxim devices, ESD protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The MAX1489E receiver inputs have extra protection against static electricity found in normal operation. Maxim's engineers developed state-of-theart structures to protect these pins against ESD of ± 15 kV without damage. After an ESD event, the MAX1489E keeps working without latchup.

ESD protection can be tested in various ways; the receiver inputs are characterized for protection to the following:

- 1) ±15kV using the Human Body Model
- 2) ±8kV using the Contact Discharge method specified in IEC1000-4-2 (formerly IEC801-2)
- ±15kV using the Air-Gap Discharge method specified in IEC1000-4-2 (formerly IEC801-2).

ESD Test Conditions

Contact Maxim for a reliability report that documents test setup, methodology, and results.

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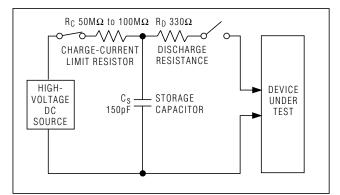


Figure 3a. IEC1000-4-2 ESD Test Model

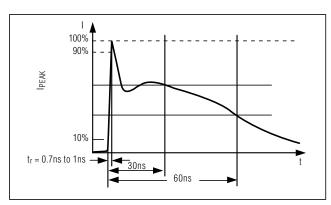


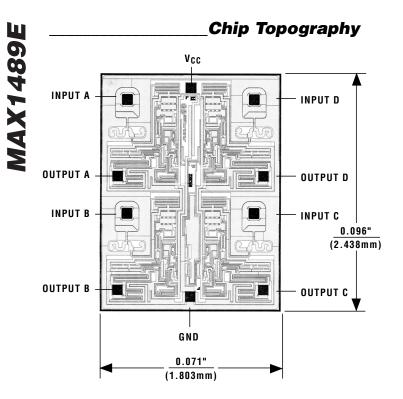
Figure 3b. IEC1000-4-2 ESD Generator Current Waveform

Applications Information

Use proper layout to ensure other devices on your board are not damaged in an ESD strike. Currents as high as 60A can instantaneously pass through the ground pin, so it is important to minimize the ground-lead return path to the power supply. A separate return path to the power supply is recommended. Trace widths should be greater than 40 mils. V_{CC} must be bypassed with 0.1µF capacitors as close to the part as possible to ensure maximum ESD protection.

Machine Model

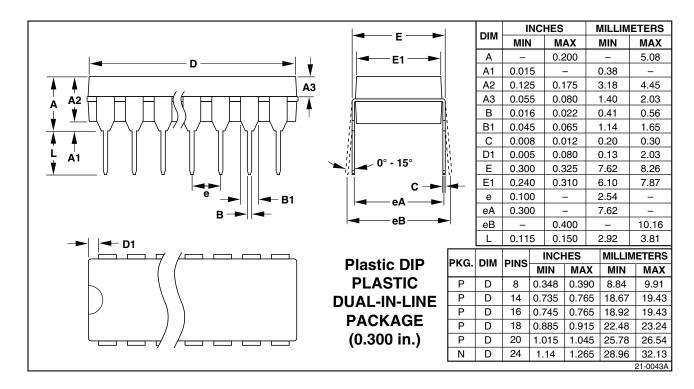
The Machine Model for ESD testing uses a 200pF storage capacitor and zero-discharge resistance. Its objective is to mimic the stress caused by contact that occurs with handling and assembly during manufacturing. Of course, all pins (not just RS-232 inputs and outputs) require this protection during manufacturing. Therefore, the Machine Model is less relevant to the I/O ports than the Human Body Model and IEC1000-4-2. **MAX1489E**



TRANSISTOR COUNT: 144 SUBSTRATE CONNECTED TO GND

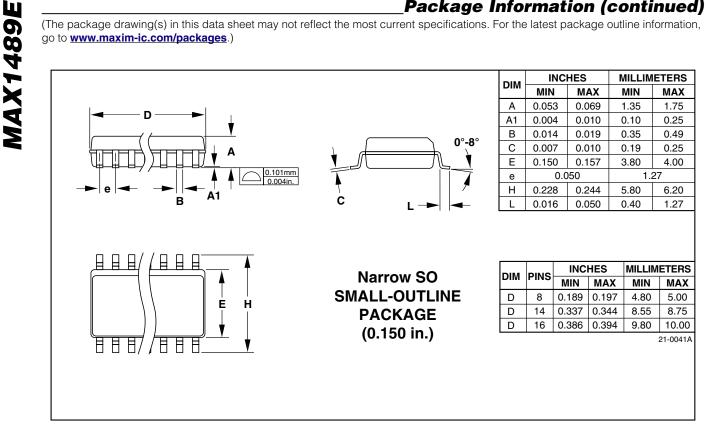
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <u>www.maxim-ic.com/packages</u>.)



Package Information (continued)

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